

Enhancement Mode N-Channel Power MOSFET

SOT23/NMOS/40V/ \pm 20V/1.2V/5A/29m Ω

Rev1.0





40V, $29m\Omega$, 5A, N-Channel MOSFET

1.Features

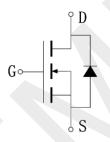
- Advanced Trench Technology
- ◆ Surface mount package

2.Applications

- ◆ Power Management
- Load Switching



V _{DS}	R _{DS(on)} Typ.	I _D .
40V	29mΩ @ 10V	
	36mΩ @ 4.5V	5A



Schematic Diagram

3. Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WP2318	*	SOT23	3,000	180,000

4.Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	V _{DSS}	40	V
Gate to Source Voltage	V_{GSS}	±20	٧
Drain Current (DC)	ID	5	Α
Drain Current (Pulse), PW≤300μs	I _{DP}	20	А
Total Dissipation	P _D	1.56	W
Thermal Resistance Junction-Ambient	R ₀ JA	80	°C/W
Junction Temperature	Tj	150	°C
Storage Temperature	T_{stg}	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



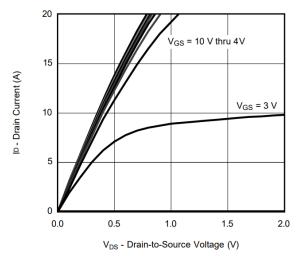
5.Electrical Characteristics at Ta=25°C (Note 2)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Drain to Source Breakdown Voltage	V _{(BR)DSS}	$I_D = 250 \mu A$, $V_{GS} = 0 V$	40	ı	-	V
Zero-Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V	-	ı	1	uA
Gate to Source Leakage Current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	ı	±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	V _{DS} =V _{GS} , I _{DS} =250μA	0.7	1.2	2.0	V
Static Drain to Source On-State		I _D =5A, V _{GS} =10V		29	38	mΩ
Resistance	R _{DS(on)}	I _D =4A, V _{GS} = 4.5V		36	52	mΩ
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =20V,		340		pF
Output Capacitance	Coss			60		pF
Reverse Transfer Capacitance	Crss	Frequency=1.0MHz		30		pF
Turn-ON Delay Time	t _{d(on)}			4.1		ns
Rise Time	t _r	V _{DD} =20V, I _D =3.5A,		11.6		ns
Turn-OFF Delay Time	$t_{\text{d(off)}}$	$R_G = 1\Omega$, $V_{GS} = 4.5V$		24		ns
Fall Time	t _f			7.6		ns
	Qg	V _{DS} = 20V,		5.8		nC
Total Gate Charge	Qgs	V _{GS} = 10V,		0.4		nC
	Qgd	I _D = 5A		2		nC
Diode Forward Voltage	V _{FSD}	I _{SD} =5A, V _{GS} = 0	0.5	0.86	1.2	V

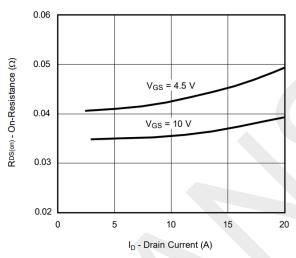
Note 2: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.



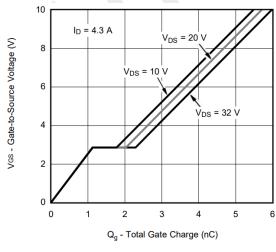
6. Typical Electrical and Thermal Characteristics



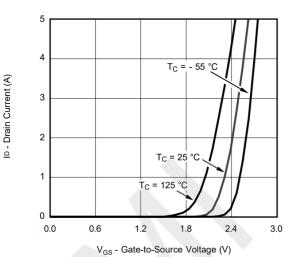
Output Characteristics



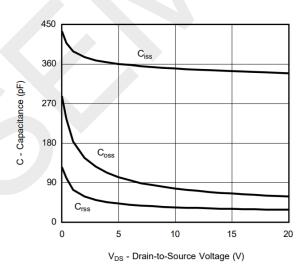
On-Resistance vs. Drain Current and Gate Voltage



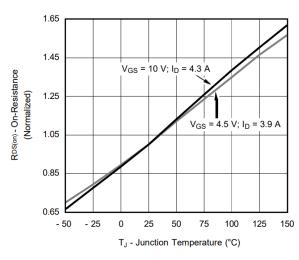
Gate Charge



Transfer Characteristics



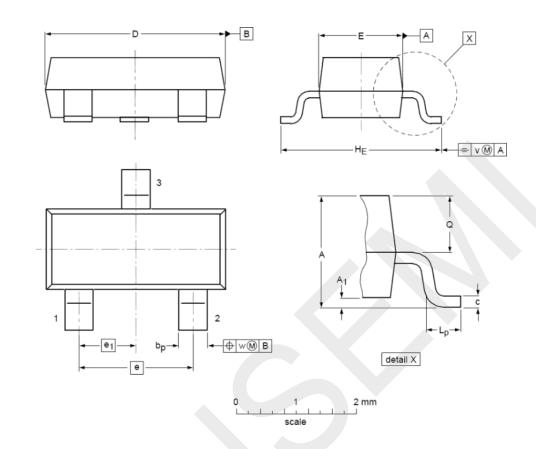
Capacitance Characteristics



On-Resistance vs. Junction Temperature



7.Package Dimensions



DIMENSIONS (unit : mm)

Symbol	Min	Тур	Max	Symbol	Min	Тур	Max
Α	0.90	1.01	1.15	A ₁	0.01	0.05	0.10
bp	0.30	0.42	0.50	С	0.08	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
е	-	1.90		e ₁		0.95	
HE	2.25	2.40	2.55	Lp	0.30	0.42	0.50
Q	0.45	0.49	0.55	v		0.20	
w		0.10					



8.Important Notice

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